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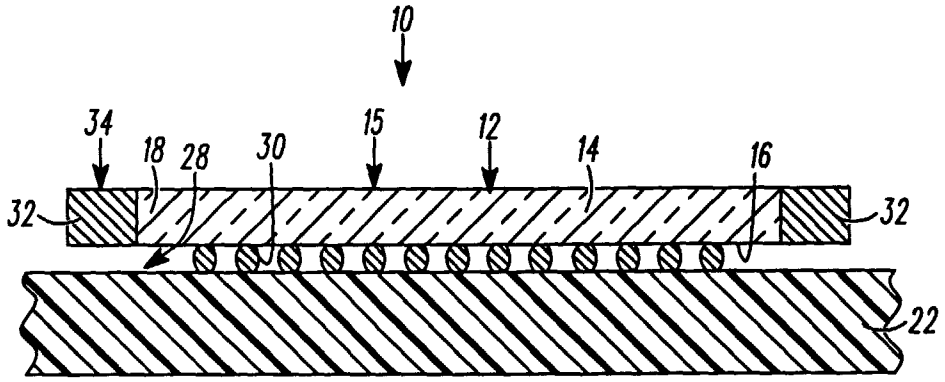
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(54) Title: MICROELECTRONIC ASSEMBLY WITH DIE SUPPORT AND METHOD



(57) Abstract: A microelectronic assembly (6) includes a substrate (22) having a plurality of bond pads disposed on a substantially planar die attach surface and an integrated circuit die (12) having a die face and a plurality of bond pads of the die (12) face. The die is provided with a polymeric bead (32) about the outer edges of the die. Die face bond pads are aligned with corresponding substrate bond pads and electrically interconnected by heating to a reflow temperature. Exposure of the polymeric bead (32) to the reflow temperature causes the bead to form a peripheral bond between the die and the substrate (22).

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